



iEDX-150T

Type : sp10, sp30, sp40, mp30, mp40
Coating/Plating Thickness Analyzer



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X-ray tube	• Mo/Rh/W/Ag Target(Optional), 50kVp, 1mA
Detection System	• Si-Pin Diode, (Option : Proportional Counter, SDD)
Energy Resolution	• Si-Pin Diode : 149eV FWHM at Mn K α Option (P C : 800eV FWHM at Mn K α SDD : 125eV FWHM at Mn K α
Collimator	• 0.3 Collimator (Option : 0.05, 0.1, 0.2, 0.5, 1mm) Manual / Auto Changing Stage
Detection Element	• Al(13) - U(92)
Sample Type	• Solid / Liquid / Powder, Multi-Layer
Size of the sample chamber	• 390mm X 410mm X 100mm (W x D x H) • Auto / Manual Stage Mode
Key Features	• Plating thickness measurement : General, Rh, Pd, Au, Ag, Sn, Ni • Film thickness measurement of multilayer thin films. (up to 5 Layer)
Camera Magnification	• 40~80 x
Safety	• 3 point interlock
Type of Report	• Excel, PDF / output • Custom form
Key Benefits	• Film thickness measurement of multilayer thin films, (up to 5 Layer) • Convenient stage control • Multi-point measurement possible • RoHS Screening(Optional) • Remote Support by Online
Application	• Product screening international environmental regulations (RoHS, WEEE, ELV compliant) • Hazardous material(Cr, Br, Cd, Hg, Pb, Cl, Sb, Sn, S) Screening equipment • Plating analysis automobile parts, Electronic circuit board (PCB), Such as a capacitor • Analysis of single-layer, Multi-layer, Alloy plating • Thickness with Composition Ratio can be measure on time in alloy plating